

QUADRUPLE LOW-POWER DIFFERENTIAL RECEIVER

Check for Samples: [SN55LBC173-HIREL](#)

FEATURES

- Meets EIA Standards RS-422-A, RS-423-A, RS-485, and CCITT V.11
- Designed to Operate With Pulse Durations as Short as 20 ns
- Designed for Multipoint Bus Transmission on Long Bus Lines in Noisy Environments
- Input Sensitivity: ± 200 mV
- Low-Power Consumption: 20 mA (Max)
- Open-Circuit Fail-Safe Design

DESCRIPTION

The SN55LBC173 is a monolithic quadruple differential line receiver with 3-state outputs designed to meet the requirements of the EIA standards RS-422-A, RS-423-A, RS-485, and CCITT V.11. This device is optimized for balanced multipoint bus transmission at data rates up to and exceeding 10 million bits per second. The four receivers share two ORed enable inputs, one active when high, the other active when low. Each receiver features high input impedance, input hysteresis for increased noise immunity, and input sensitivity of ± 200 mV over a common-mode input voltage range of 12 V to -7 V. Fail-safe design ensures that if the inputs are open circuited, the output is always high. The SN55LBC173 is designed using the Texas Instruments proprietary LinBiCMOS™ technology that provides low power consumption, high switching speeds, and robustness.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

LinBiCMOS is a trademark of Texas Instruments.



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

ORDERING INFORMATION⁽¹⁾

| T _A | PACKAGE | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|----------------|---------|-----------------------|------------------|
| -55°C to 125°C | KGD | SN55LBC173MKGD1 | NA |
| | | SN55LBC173MKGD2 | NA |

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

BARE DIE INFORMATION

| DIE THICKNESS | BACKSIDE FINISH | BACKSIDE POTENTIAL | BOND PAD METALLIZATION COMPOSITION | BOND PAD THICKNESS |
|---------------|------------------------|--------------------|------------------------------------|--------------------|
| 10.5 mils. | Silicon with backgrind | Floating | AlSi(1%)Cu(0.5%)TiW | 1850 nm |

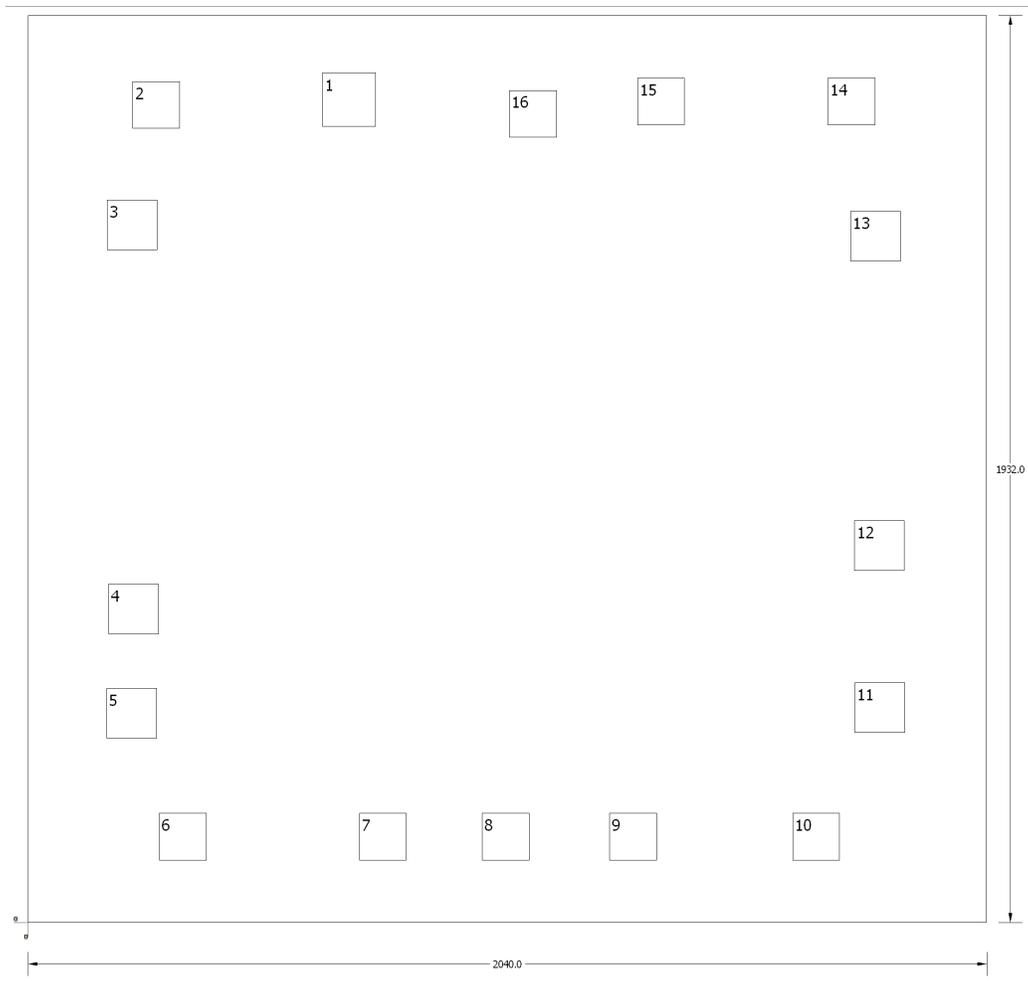


Table 1. Bond Pad Coordinates in Microns

| DESCRIPTION | PAD NUMBER | X MIN | Y MIN | X MAX | Y MAX |
|-------------|------------|--------|--------|--------|--------|
| 1B | 1 | 626.5 | 1695 | 740.5 | 1809.5 |
| 1A | 2 | 222.5 | 1690.7 | 323 | 1791.3 |
| 1Y | 3 | 167.9 | 1432.1 | 274.8 | 1539 |
| G | 4 | 171.4 | 614.1 | 278.3 | 721 |
| 2Y | 5 | 166.6 | 392.1 | 273.5 | 499 |
| 2A | 6 | 279.2 | 132 | 379.7 | 232.6 |
| 2B | 7 | 704.8 | 132 | 805.3 | 232.6 |
| GND | 8 | 966.2 | 132 | 1066.7 | 232.6 |
| 3B | 9 | 1237.2 | 132 | 1337.7 | 232.6 |
| 3A | 10 | 1626.7 | 132 | 1727.2 | 232.6 |
| 3Y | 11 | 1758.7 | 403.7 | 1865.6 | 510.6 |
| \bar{G} | 12 | 1758.5 | 749 | 1865.4 | 855.9 |
| 4Y | 13 | 1750.1 | 1408.4 | 1857 | 1515.3 |
| 4A | 14 | 1702.2 | 1698.4 | 1802.7 | 1799 |
| 4B | 15 | 1296.7 | 1698.4 | 1397.2 | 1799 |
| VCC | 16 | 1024.2 | 1671.9 | 1124.7 | 1772.5 |

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range unless otherwise noted

| | Value | UNIT |
|---|------------|------|
| V _{CC} Supply voltage range ⁽²⁾ | –0.3 to 7 | V |
| V _I Input voltage range, (A or B inputs) | ±25 | V |
| V _{ID} Differential input voltage ⁽³⁾ | ±25 | V |
| Data and control voltage range | –0.3 to 7 | V |
| T _A Operating free-air temperature range | –55 to 125 | °C |
| T _{stg} Storage temperature range | –65 to 150 | °C |

- (1) Stresses beyond those listed under *absolute maximum ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values are with respect to network ground terminal.
- (3) Differential input voltage is measured at the noninverting input with respect to the corresponding inverting input.

RECOMMENDED OPERATING CONDITIONS

| | MIN | TYP | MAX | UNIT |
|---|------|-----|------|------|
| V _{CC} Supply voltage | 4.75 | 5 | 5.25 | V |
| V _{IC} Common-mode input voltage | –7 | | 12 | |
| V _{IH} High-level input voltage | 2 | | | |
| V _{IL} Low-level input voltage | | | 0.8 | |
| V _{ID} Differential input voltage | –6 | | 6 | |
| I _{OH} High-level output current | | | –8 | mA |
| I _{OL} Low-level output current | | | 16 | mA |
| T _A Operating free-air temperature | –55 | | 125 | °C |

ELECTRICAL CHARACTERISTICS

over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

| PARAMETER | | TEST CONDITIONS | MIN | TYP ⁽¹⁾ | MAX | UNIT | |
|------------------|---|--|---------------------|---|------|------|----|
| V _{IT+} | Positive-going input threshold voltage | I _O = -8 mA | | | 0.2 | V | |
| V _{IT-} | Negative-going input threshold voltage | I _O = 8 mA | -0.2 | | | V | |
| V _{hys} | Hysteresis voltage (V _{IT+} - V _{IT-}) | | | 45 | | mV | |
| V _{IK} | Enable input clamp voltage | I _I = -18 mA | | -0.9 | -1.5 | V | |
| V _{OH} | High-level output voltage | V _{ID} = -200 mV, I _{OH} = -8 mA | 3.5 | 4.5 | | V | |
| V _{OL} | Low-level output voltage | V _{ID} = -200 mV, I _{OL} = 8 mA | | 0.3 | 0.5 | V | |
| | | V _{ID} = -200 mV, I _{OL} = 8 mA, T _A = 125° | | | 0.7 | | |
| I _{OZ} | High-impedance-state output current | V _O = 0 V to V _{CC} | | | ±20 | μA | |
| I _I | Bus input current | A or B inputs | Other inputs at 0 V | V _{IH} = 12 V, V _{CC} = 5 V | 0.7 | 1.15 | mA |
| | | | | V _{IH} = 12 V, V _{CC} = 0 V | 0.8 | 1.15 | |
| | | | | V _{IH} = -7 V, V _{CC} = 5 V | -0.5 | -0.9 | |
| | | | | V _{IH} = -7 V, V _{CC} = 0 V | -0.4 | -0.9 | |
| I _{IH} | High-level input current | V _{IH} = 5 V | | | ±20 | μA | |
| I _{IL} | Low-level input current | V _{IL} = 0 V | | | -20 | μA | |
| I _{OS} | Short-circuit output current | V _O = 0 | | -80 | -120 | mA | |
| I _{CC} | Supply current | Outputs enabled, I _O = 0, V _{ID} = 5 V | | 11 | 20 | mA | |
| | | Outputs disabled | | 0.9 | 1.4 | | |

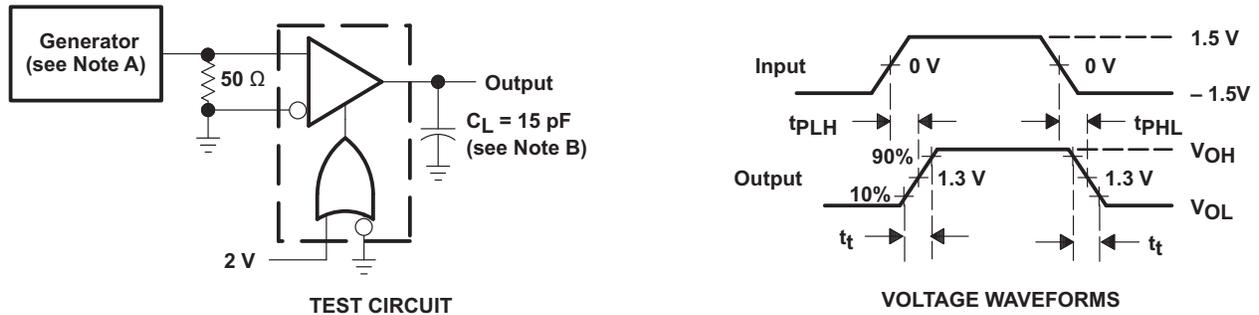
(1) All typical values are at 25°C and with a 5 V supply.

SWITCHING CHARACTERISTICS

V_{CC} = 5 V, C_L = 15 pF, over operating free-air temperature range (unless otherwise noted)

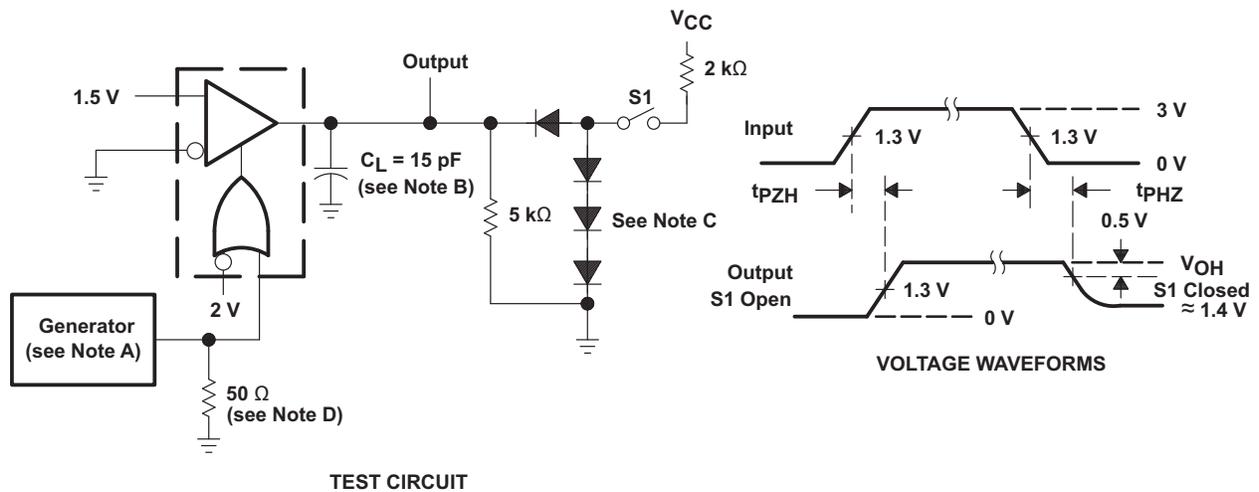
| PARAMETER | | TEST CONDITIONS | T _A | MIN | TYP | MAX | UNIT |
|--------------------|---|--|----------------|-----|-----|-----|------|
| t _{PHL} | Propagation delay time, high-to-low-level output | V _{ID} = -1.5 V to 1.5 V, See Figure 1 | 25°C | 11 | 22 | 30 | ns |
| | | | -55°C to 125°C | 11 | | 35 | |
| t _{PLH} | Propagation delay time, low-to-high-level output | V _{ID} = -1.5 V to 1.5 V, See Figure 1 | 25°C | 11 | 22 | 35 | ns |
| | | | -55°C to 125°C | 11 | | 35 | |
| t _{PZH} | Output enable time to high level | See Figure 2 | 25°C | | 17 | 40 | ns |
| | | | -55°C to 125°C | | | 45 | |
| t _{PZL} | Output enable time to low level | See Figure 3 | 25°C | | 18 | 30 | ns |
| | | | -55°C to 125°C | | | 35 | |
| t _{PHZ} | Output disable time from high level | See Figure 2 | 25°C | | 30 | 40 | ns |
| | | | -55°C to 125°C | | | 55 | |
| t _{PLZ} | Output disable time from low level | See Figure 3 | 25°C | | 25 | 40 | ns |
| | | | -55°C to 125°C | | | 45 | |
| t _{sk(p)} | Pulse skew (t _{PHL} - t _{PLH}) | See Figure 1 | 25°C | | 0.5 | 6 | ns |
| | | | -55°C to 125°C | | | 7 | |
| t _t | Transition time | See Figure 1 | 25°C | | 5 | 10 | ns |
| | | | -55°C to 125°C | | | 16 | |

PARAMETER MEASUREMENT INFORMATION



- A. The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, duty cycle ≤ 50%, $t_r \leq 6$ ns, $t_f \leq 6$ ns, $Z_O = 50 \Omega$.
- B. C_L includes probe and jig capacitance.

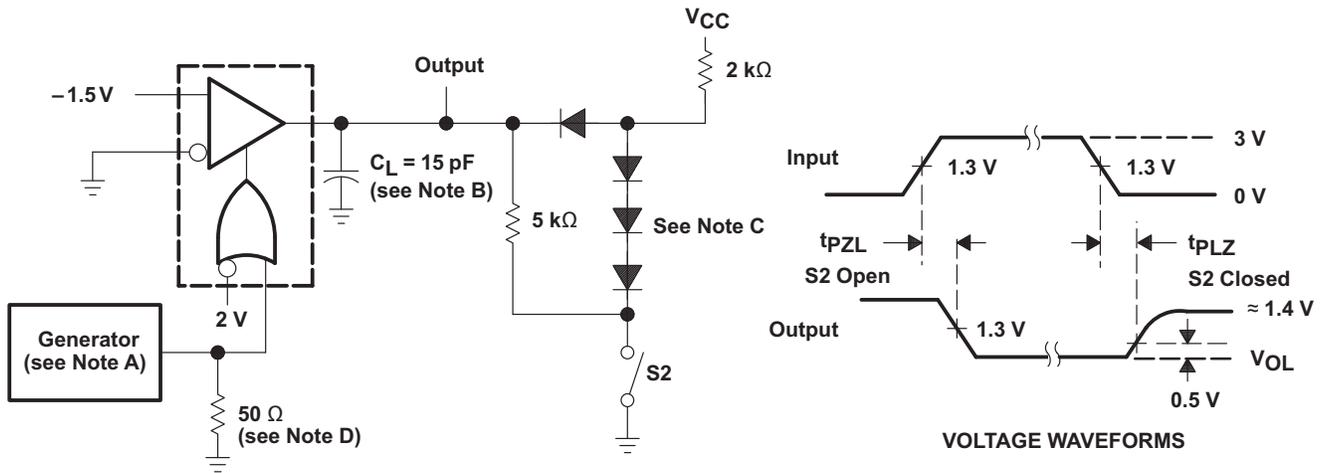
Figure 1. t_{pd} and t_t Test Circuit and Voltage Waveforms



- A. The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, duty cycle ≤ 50%, $t_r \leq 6$ ns, $t_f \leq 6$ ns, $Z_O = 50 \Omega$.
- B. C_L includes probe and jig capacitance.
- C. All diodes are 1N916 or equivalent.
- D. To test the active-low enable \overline{G} , ground G and apply an inverted input waveform to \overline{G} .

Figure 2. t_{pZH} and t_{pHZ} Test Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION (continued)



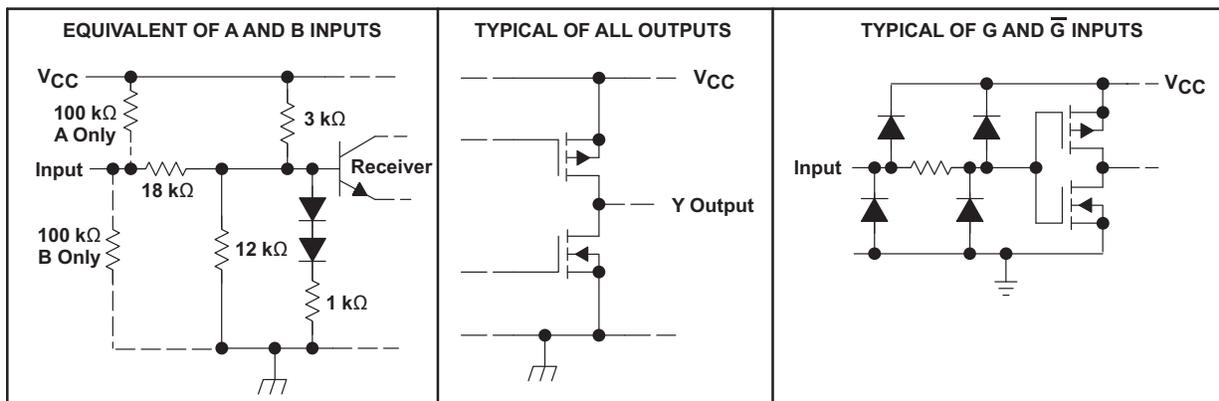
TEST CIRCUIT

- A. The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, duty cycle ≤ 50%, $t_r \leq 6$ ns, $t_f \leq 6$ ns, $Z_O = 50 \Omega$.
- B. C_L includes probe and jig capacitance.
- C. All diodes are 1N916 or equivalent.
- D. To test the active-low enable \overline{G} , ground G and apply an inverted input waveform to \overline{G} .

Figure 3. t_{pZL} and t_{pLZ} Test Circuit and Voltage Waveforms

DEVICE INFORMATION

EQUIVALENT INPUT AND OUTPUT SCHEMATIC DIAGRAMS



FUNCTION TABLE (EACH RECIEVER)

| DIFFERENTIAL INPUTS | ENABLES | | OUTPUT |
|-------------------------|---------|-----------|--------|
| | G | \bar{G} | |
| $V_{ID} \geq 0.2 V$ | H | X | H |
| $V_{ID} < 0.2 V$ | X | L | H |
| $-0.2 < V_{ID} < 0.2 V$ | H | X | ? |
| $V_{ID} < -0.2 V$ | X | L | ? |
| $V_{ID} \leq -0.2 V$ | H | X | L |
| X | X | L | L |
| Open circuit | H | X | H |
| | X | L | H |

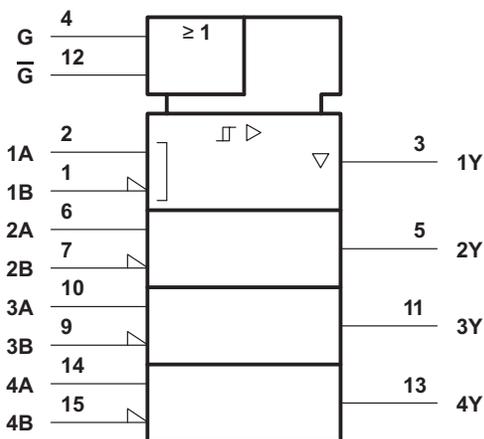


Figure 4. Logic Symbol

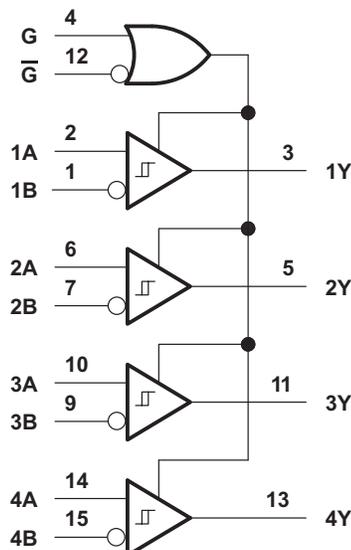


Figure 5. Logic Diagram (Positive Logic)

TYPICAL CHARACTERISTICS

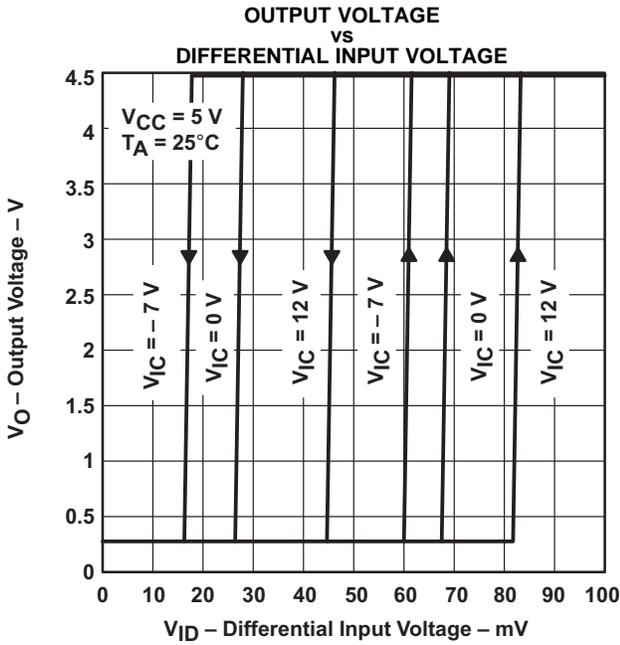


Figure 6.

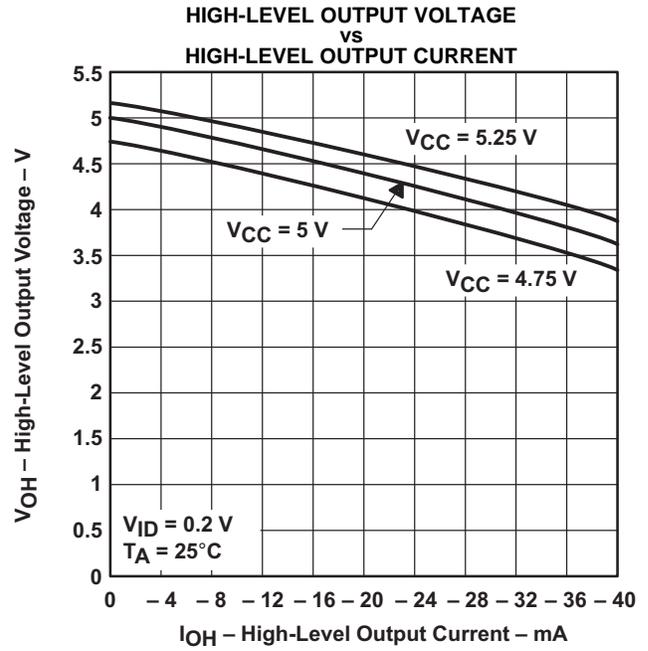


Figure 7.

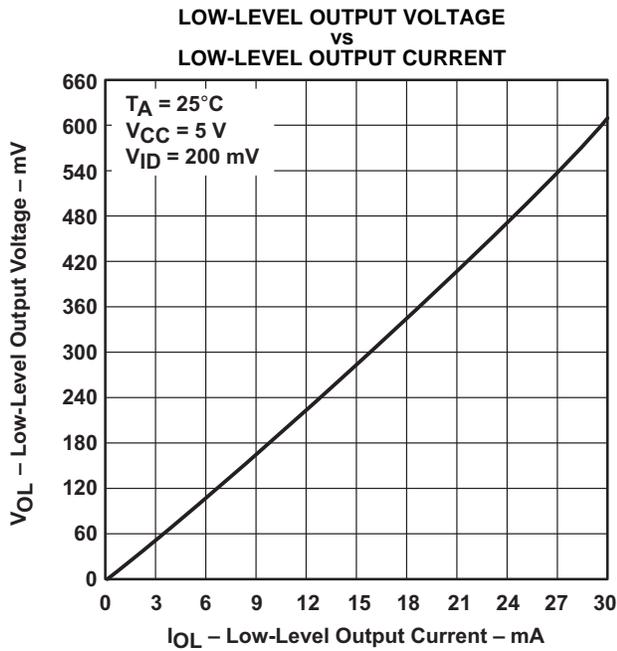


Figure 8.

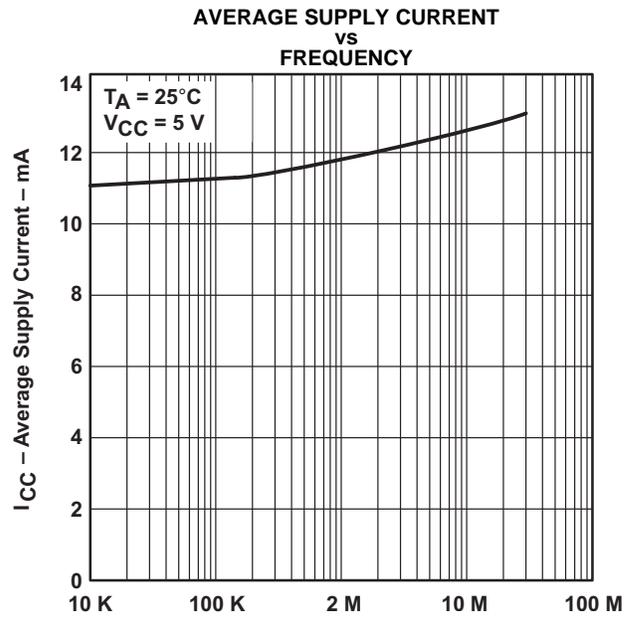
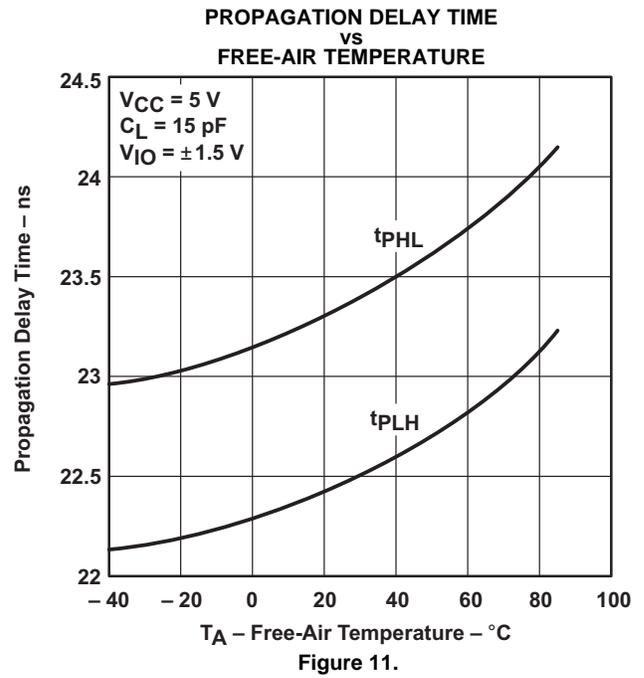
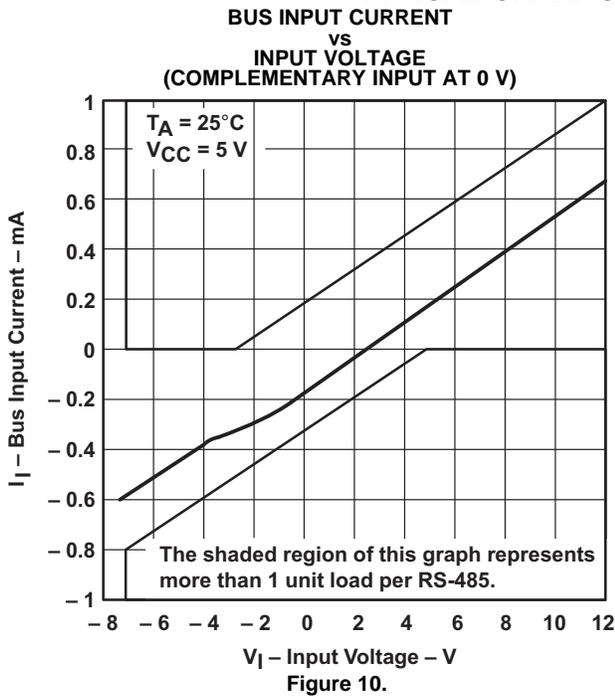


Figure 9.

TYPICAL CHARACTERISTICS (continued)



PACKAGING INFORMATION

| Orderable part number | Status (1) | Material type (2) | Package Pins | Package qty Carrier | RoHS (3) | Lead finish/ Ball material (4) | MSL rating/ Peak reflow (5) | Op temp (°C) | Part marking (6) |
|-----------------------|---------------|----------------------|-----------------|-----------------------|-------------|--------------------------------------|-----------------------------------|--------------|---------------------|
| SN55LBC173MKGD1 | Active | Production | XCEPT (KGD) 0 | 100 TUBE | Yes | Call TI | N/A for Pkg Type | -55 to 125 | |
| SN55LBC173MKGD1.A | Active | Production | XCEPT (KGD) 0 | 100 TUBE | Yes | Call TI | N/A for Pkg Type | -55 to 125 | |
| SN55LBC173MKGD2 | Active | Production | XCEPT (KGD) 0 | 10 TUBE | - | Call TI | Call TI | -55 to 125 | |
| SN55LBC173MKGD2.A | Active | Production | XCEPT (KGD) 0 | 10 TUBE | - | Call TI | Call TI | -55 to 125 | |

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you fully indemnify TI and its representatives against any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#), [TI's General Quality Guidelines](#), or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products. Unless TI explicitly designates a product as custom or customer-specified, TI products are standard, catalog, general purpose devices.

TI objects to and rejects any additional or different terms you may propose.

Copyright © 2026, Texas Instruments Incorporated

Last updated 10/2025